

High fluidity

Excellent fillability for narrow gap/pitch

Reduced void/bleed

Applications
IC Package/Mobile
 High-density advanced IC packages (BGA, CSP)

LEXCM^{DF}

CV5300 series

Capillary underfill (CUF) semiconductor encapsulation materials

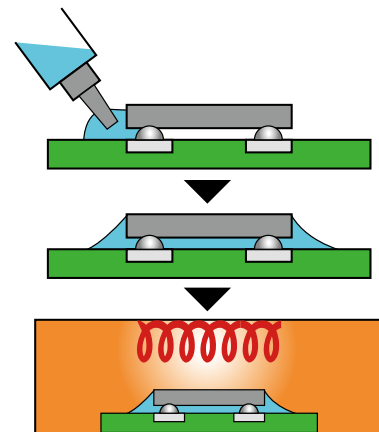
High capillary flow rate fills narrow gaps without voiding.

Line-up

Features

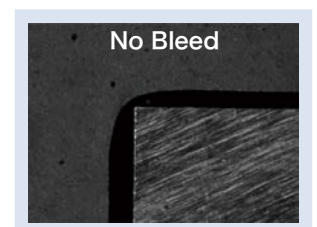
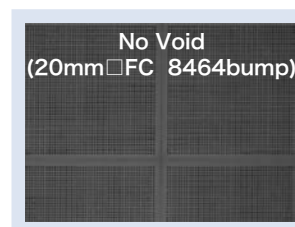
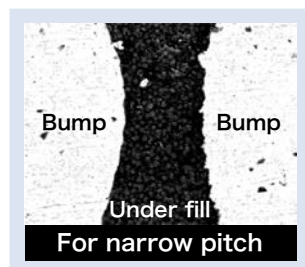
- 1 Compatible with narrow gap
- 2 Uniform penetration
- 3 High-speed fillability
- 4 Compatible with low-k film
- 5 High moisture reflow resistance

Part Number	Features
CV5300 series	High fluidity, Short-time curing



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General properties

Item	Unit	CV5300 series
Filler size Max	μm	1
C.T.E.	ppm/°C	33
Tg (TMA)	°C	110
Flexural modulus (25°C)	GPa	7

Please see our website for Notes before you use.

The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry Co., Ltd. Electronic Materials Business Division

Panasonic Industry CV5300

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